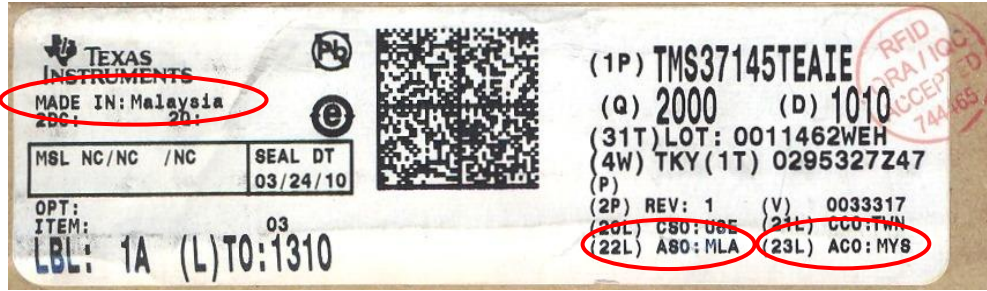


PCN Number:	20160908002	PCN Date:	Sept 19, 2016												
Title:	Assembly and Test site move from MLA to PTIAT for Select Devices														
Customer Contact:	PCN Manager	Dept:	Quality Services												
Proposed 1st Ship Date:	Dec 19, 2016	Estimated Sample Availability:	Date provided at sample request												
Change Type:															
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design												
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet												
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change												
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site												
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process												
		<input type="checkbox"/>	Wafer Bump Site												
		<input type="checkbox"/>	Wafer Bump Material												
		<input type="checkbox"/>	Wafer Bump Process												
		<input type="checkbox"/>	Wafer Fab Site												
		<input type="checkbox"/>	Wafer Fab Materials												
		<input type="checkbox"/>	Wafer Fab Process												
PCN Details															
Description of Change:															
Texas Instruments Incorporated is announcing the Assembly and Test site move from MLA to PTIAT for Select Devices listed in the "Product Affected" Section. No Material differences between Sites.															
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly Site City</th> </tr> </thead> <tbody> <tr> <td>TI Malaysia</td> <td>MLA</td> <td>MY</td> <td>Kuala Lumpur</td> </tr> <tr> <td>Powertech Technology Inc.</td> <td>PT2</td> <td>TW</td> <td>Hsinchu City</td> </tr> </tbody> </table>				Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City	TI Malaysia	MLA	MY	Kuala Lumpur	Powertech Technology Inc.	PT2	TW	Hsinchu City
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City												
TI Malaysia	MLA	MY	Kuala Lumpur												
Powertech Technology Inc.	PT2	TW	Hsinchu City												
Test coverage, insertions, conditions will remain consistent with current testing and verified via test MQ.															
Reason for Change:															
Continuity of supply.															
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):															
None															
Anticipated impact on Material Declaration															
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .												
Changes to product identification resulting from this PCN:															
Sample product shipping label (not actual product label)															
Assembly Site:															
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA													
Powertech Technology Inc.	Assembly Site Origin (22L)	ASO: PT2													
Sample product shipping label to show code location (not actual product label)															



ASSEMBLY SITE CODES: MLA=K, PT2 =C

Products Affected

LMZ31704RVQR	LMZ31707RVQR	LMZ31710RVQR	TPS84A20RVQR
LMZ31704RVQT	LMZ31707RVQT	LMZ31710RVQT	TPS84A20RVQT



Qualification Report

**LMZ31704RVQ, LMZ31707RVQ, LMZ31710RVQ
Approve Date 22-Aug-2016**

Product Attributes

Attributes	Qual Device: LMZ31710RVQ	QBS Product Family: LMZ31704RVQ	QBS Product Family: LMZ31707RVQ	QBS Product Reference: LMZ31710RVQ	QBS Package Reference: LMZ36002RVQ
Die Attributes	-	-	-	-	-
Wafer Fab Supplier	TI - Germany	TI - Germany	TI - Germany	TI - Germany	DMOS5
Wafer Process	LBC7	LBC7	LBC7	LBC7	LBC8
Assembly Site	PTI-Taiwan	PTI-Taiwan	PTI-Taiwan	TI - Malaysia	PTI-Taiwan
Package Family	QFN	QFN	QFN	QFN	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0

- QBS: Qual By Similarity
- Qual Device LMZ31704RVQ, LMZ31707RVQ, LMZ31710RVQ are qualified at LEVEL3-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMZ31710RVQ	QBS Product Reference: LMZ31710RVQ	QBS Package Reference: LMZ36002RVQ
PC	Preconditioning Level 3	260C	1/231/0	-	3/231/0
HTOL	Life Test, 125C	1000 hours	1/77/0	2/154/0	-
PTCL	Power Temperature Cycle, 25C/70C	1000 hours	1/40/0	-	-
HTSL	High Temp Storage Bake 150C	1000 hours	1/77/0	-	1/77/0
TC	Temperature Cycle, -65/150C	500 cycles	1/77/0	-	-
TC	Temperature Cycle, -55/125C	700 cycles	-	-	3/231/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 hours	1/77/0	-	1/77/0
UHAST	Unbiased HAST 110C/85%RH	264 hours	1/77/0	-	3/231/0
HBM	ESD HBM	1500V	-	0/3	-
CDM	ESD CDM	750V	-	0/3	-
ED	Electrical Characterization	-	Pass	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com